Docket No. 5853-224

## PATENT APPLICATION TRANSMITTAL LETTER

Commissioner for Patents **BOX PATENT APPLICATION** Washington, DC 20231

Transmitted herewith for filing of the patent application of:

Inventor(s):

Rajiv K. Singh

Seung-Mahn Lee



## for <u>SLURRY AND METHOD FOR CHEMICAL MECHANICAL POLISHING OF METAL STRUCTURES</u> INCLUDING REFRACTORY METAL BASED BARRIER LAYERS

are the following:

- Specification, including Abstract <u>X</u>
- Sheets of drawing (3 sets) \_10
- Executed Declaration and Power of Attorney
- Assignment with Recordation Cover Sheet
- Other: 2 postcards

	CLAIMS AS FILED		
FOR	NO. FILED	NO. EXTRA	
Basic Fee	y y		
Total Claims	71	51	
Indep Claims	6	3	
multiple dependent claim present No			

If the difference in Col. 1 is less than zero, enter "0" in Col. 2 **Assignment Recordation** 

Small Entity	
RATE	FEE
And the second s	\$ 370.00
x \$ 9 =	\$ 459.00
x \$ 42 =	\$126.00
x \$135 =	\$
TOTAL	\$ 955.00 \$ 40.00

Other than a Small Entity		
RATE	FEE	
and the state of t	\$ 740.00	
x \$ 18 =	\$	
x \$ 84 =	\$	
x \$270 =	\$	
TOTAL	\$	

- You are hereby authorized to charge \$995.00 to Deposit Account 50-0951.
- <u>X</u> <u>X</u> The Commissioner is hereby authorized to charge any underpayment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0951. A duplicate of this sheet is enclosed.
- Any additional filing fees required under 37 C.F.R. 1.16.
- Any patent application processing fees under 37 C.F.R. 1.1

Registration No.46,803